# ECE 342 Electronic Circuits

# Lecture 3 PN Junctions and Diodes

Jose E. Schutt-Aine Electrical & Computer Engineering University of Illinois jesa@illinois.edu



# Definitions

*B*: material dependent parameter =  $5.4 \times 10^{31}$  for Si

 $E_G$ : Bandgap energy = 1.12 eV

*k*: Boltzmann constant= $8.62 \times 10^{-5}$  ev/K

 $n_i$ : intrinsic carrier concentration

At T = 300 K,  $n_i = 1.5 \times 10^{10}$  carriers/cm<sup>3</sup>

 $J_p$ : hole current density A/m<sup>2</sup>

$$J_n^{F}$$
: electron current density A/m<sup>2</sup>

*q*: electron charge

 $D_p$ : Diffusion constant (diffusivity) of holes

 $D_n^{P}$ : Diffusion constant (diffusivity) of electrons

$$\mu_{p}$$
: mobility for holes = 480 cm<sup>2</sup> /V sec

 $\mu_n$ : mobility for electrons = 1350 cm<sup>2</sup> /V sec

 $N_D$ : concentration of donor atoms

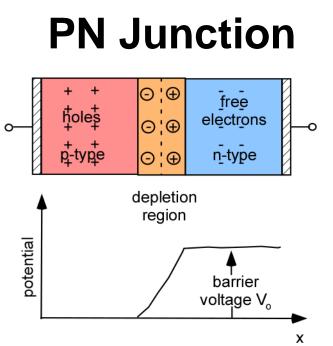
 $n_{no}$ : concentration of free electrons at thermal equilibrium

 $N_A$ : concentration of acceptor atoms

 $p_{po}$ : concentration of holes at thermal equilibrium

Einstein Relation :  $\frac{D_n}{\mu_n} = \frac{D_p}{\mu_p} = \frac{kT}{q} = V_T$ : thermal voltage





- When a p material is connected to an n-type material, a junction is formed
  - Holes from p-type diffuse to n-type region
  - Electrons from n-type diffuse to p-type region
  - Through these diffusion processes, recombination takes place
  - Some holes disappear from p-type
  - Some electrons disappear from n-type

#### A depletion region consisting of bound charges is thus formed Charges on both sides cause electric field $\rightarrow$ potential = $V_o$



# **PN Junction**

- Potential acts as <u>barrier</u> that must be overcome for holes to diffuse into the n-region and electrons to diffuse into the p-region
- Open circuit: No external current

#### Junction built-in voltage

From principle of detailed balance and equilibrium we get:

$$V_o = V_T \ln\left(\frac{N_A N_D}{n_i^2}\right)$$

For Si, V<sub>o</sub> is typically 0.6V to 0.8V

Charge equality in depletion region gives:

$$qx_pAN_A = qx_nAN_D$$

A: cross-section of junction  $x_p$ : width in p side  $x_n$ : width in n side

 $\varepsilon_s$  : silicon permittivity  $\varepsilon_s = 11.7\varepsilon_o = 1.04 \times 10^{-8}$  F/m

$$\frac{x_n}{x_p} = \frac{N_A}{N_D}$$

$$W_{dep} = x_n + x_p = \sqrt{\frac{2\varepsilon_s}{q} \left(\frac{1}{N_A} + \frac{1}{N_D}\right)} V_o$$



### Example

Find the barrier voltage across the depletion region of a silicon diode at T = 300 K with  $N_D = 10^{15}$ /cm<sup>3</sup> and  $N_A = 10^{18}$ /cm<sup>3</sup>.

Use 
$$V_o = V_T \ln\left(\frac{N_A N_D}{n_i^2}\right)$$
  
@ 300K,  
 $n_i = 1.5 \times 10^{10} / \text{cm}^3$   
 $V_T = 0.026 \text{ V}$ 

$$V_o = \psi_o = 0.026 \ln\left(\frac{10^{18} \cdot 10^{15}}{(1.5)^2 \times 10^{20}}\right) = 0.026 \ln\left[\frac{10^{13}}{2.25}\right]$$

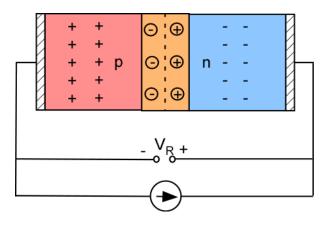
 $V_o = \psi_o = 0.026 \times 29.12 = 0.7571$  volts

 $V_o = \psi_o = 0.7571$  volts



ECE 342 – Jose Schutt-Aine

# **PN Junction under Reverse Bias**



#### • When a reverse bias is applied

- Transient occurs during which depletion capacitance is charged to new bias voltage
- Increase of space charge region
- Diffusion current decreases
- Drift current remains constant
- Barrier potential is increased
- A steady state is reached
- − After transient: steady-state reverse current =  $I_S$ - $I_D$  ( $I_D$  is very small) → reverse current ~  $I_S$  ~ 10<sup>-15</sup> A

#### Under reverse bias the current in the diode is negligible



### **Depletion Layer Stored Charge**

$$q_j = q_N = q N_D x_n A$$

A: cross section area  $q_j$ : stored charge

Let  $W_{dep}$  = depletion-layer width

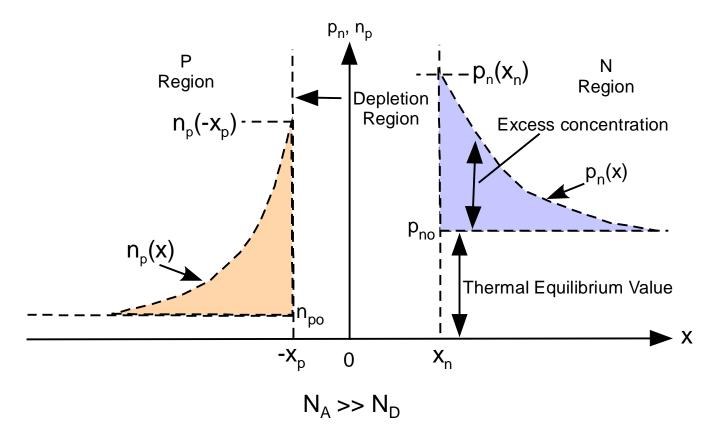
$$q_j = q \frac{N_A N_D}{N_A + N_D} A W_{dep}$$

The total voltage across the depletion layer is  $V_o + V_R$ 

$$W_{dep} = \sqrt{\frac{2\varepsilon_s}{q} \left(\frac{1}{N_A} + \frac{1}{N_D}\right) \left(V_o + V_R\right)}$$



### **Forward-Biased Junction Carrier Distribution**



#### Barrier voltage is now lower than $V_o$

In steady state, concentration profile of <u>excess minority carriers</u> remains constant



### **Forward-Biased PN Junction**

**Diode equation:**  $I_D = I_S \left( e^{V/nV_T} - 1 \right)$ 

$$I_{S} = Aqn_{i}^{2} \left( \frac{D_{p}}{L_{p}N_{D}} + \frac{D_{n}}{L_{n}N_{A}} \right)$$

since 
$$n_i^2$$
 is a strong function of temperature; thus  $I_s$  is a strong function of temperature

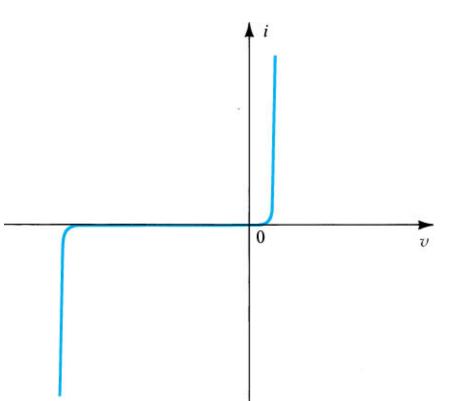
*n* has a value between 1 and 2. Diodes made using standard IC process have n=1; discrete diodes have n=1

### In general, assume *n*=1

If  $V \gg V_T$ , we can use  $I_D \approx I_S e^{V/V_T}$ 



### **Diode Characteristics**

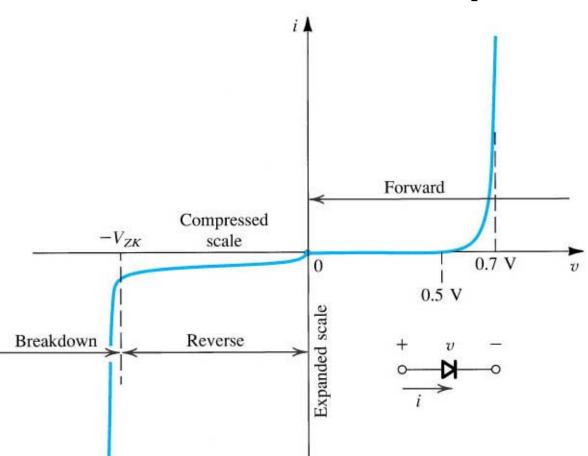


#### • Three distinct regions

- The forward-bias region, determined by v > 0
- The reverse-bias region, determined by v < 0
- The breakdown region, determined by  $v < -V_{ZK}$



### **Diode I-V Relationship**



#### Breakdown

 Electric field strong enough in depletion layer to break covalent bonds and generate electron-hole pairs. Electrons are then swept by E-field into the nside. Large number of carriers for a small increase in junction voltage

